

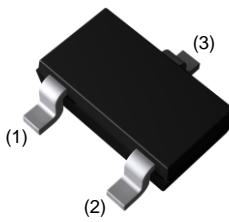
V_{DSS}	100V
$R_{DS(on)}$ (Max.)	520mΩ
I_D	1.0A
P_D	1.0W

●Features

- 1) Low on - resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (TSMT3).
- 4) Pb-free lead plating ; RoHS compliant

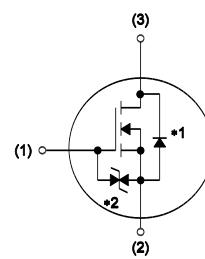
●Outline

TSMT3



●Inner circuit

- (1) Gate
- (2) Source
- (3) Drain



*1 ESD PROTECTION DIODE
*2 BODY DIODE

●Packaging specifications

Type	Packaging	Taping
	Reel size (mm)	180
	Tape width (mm)	8
	Basic ordering unit (pcs)	3,000
	Taping code	TL
	Marking	ZJ

●Absolute maximum ratings($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	100	V
Continuous drain current	I_D *1	± 1	A
Pulsed drain current	$I_{D,pulse}$ *2	± 4	A
Gate - Source voltage	V_{GSS}	± 20	V
Power dissipation	P_D *3	1.0	W
	P_D *4	0.54	W
Junction temperature	T_j	150	°C
Range of storage temperature	T_{stg}	-55 to +150	°C

● Thermal resistance

Parameter	Symbol	Values			Unit
		Min.	Typ.	Max.	
Thermal resistance, junction - ambient	R_{thJA} ^{*3}	-	-	125	°C/W
Thermal resistance, junction - ambient	R_{thJA} ^{*4}	-	-	231	°C/W

● Electrical characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = 1\text{mA}$	100	-	-	V
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$I_D = 1\text{mA}$ referenced to 25°C	-	115	-	mV/°C
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 100\text{V}, V_{GS} = 0\text{V}$	-	-	1	μA
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$	-	-	± 10	μA
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = 10\text{V}, I_D = 1\text{mA}$	1.0	-	2.5	V
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{(GS)\text{th}}}{\Delta T_j}$	$I_D = 1\text{mA}$ referenced to 25°C	-	-3.7	-	mV/°C
Static drain - source on - state resistance	$R_{DS(on)}$ ^{*5}	$V_{GS}=10\text{V}, I_D=1\text{A}$ $V_{GS}=4.5\text{V}, I_D=1\text{A}$ $V_{GS}=4.0\text{V}, I_D=1\text{A}$ $V_{GS}=10\text{V}, I_D=1\text{A}, T_j=125^\circ\text{C}$	- - - -	370 400 410 710	520 560 580 1000	mΩ
Gate input resistannce	R_G	f = 1MHz, open drain	-	10	-	Ω
Transconductance	g_{fs} ^{*5}	$V_{DS} = 10\text{V}, I_D = 1\text{A}$	1.0	3.1	-	S

*1 Limited only by maximum temperature allowed.

*2 Pw ≤ 10μs, Duty cycle ≤ 1%

*3 Mounted on a ceramic board (30x30x0.8mm)

*4 Mounted on a FR4 (12x20x0.8mm)

*5 Pulsed

●Electrical characteristics($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Input capacitance	C_{iss}	$V_{GS} = 0\text{V}$ $V_{DS} = 25\text{V}$ $f = 1\text{MHz}$	-	140	-	pF
Output capacitance	C_{oss}		-	20	-	
Reverse transfer capacitance	C_{rss}		-	12	-	
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \approx 50\text{V}, V_{GS} = 10\text{V}$ $I_D = 0.5\text{A}$ $R_L = 100\Omega$ $R_G = 10\Omega$	-	6	-	ns
Rise time	t_r^{*5}		-	9	-	
Turn - off delay time	$t_{d(off)}^{*5}$		-	22	-	
Fall time	t_f^{*5}		-	15	-	

●Gate Charge characteristics($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Total gate charge	Q_g^{*5}	$V_{DD} \approx 50\text{V}, I_D = 1\text{A}$ $V_{GS} = 5\text{V}$	-	3.5	-	nC
		$V_{DD} \approx 15\text{V}, I_D = 9\text{A}$ $V_{GS} = 10\text{V}$	-	7	14	
Gate - Source charge	Q_{gs}^{*5}	$V_{DD} \approx 50\text{V}, I_D = 1\text{A}$ $V_{GS} = 5\text{V}$	-	0.9	-	
Gate - Drain charge	Q_{gd}^{*5}		-	0.8	-	

●Body diode electrical characteristics (Source-Drain)($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Conditions	Values			Unit
			Min.	Typ.	Max.	
Inverse diode continuous, forward current	I_s^{*1}	$T_a = 25^\circ\text{C}$	-	-	0.8	A
Forward voltage	V_{SD}^{*5}	$V_{GS} = 0\text{V}, I_s = 1\text{A}$	-	-	1.2	V

●Electrical characteristic curves

Fig.1 Power Dissipation Derating Curve

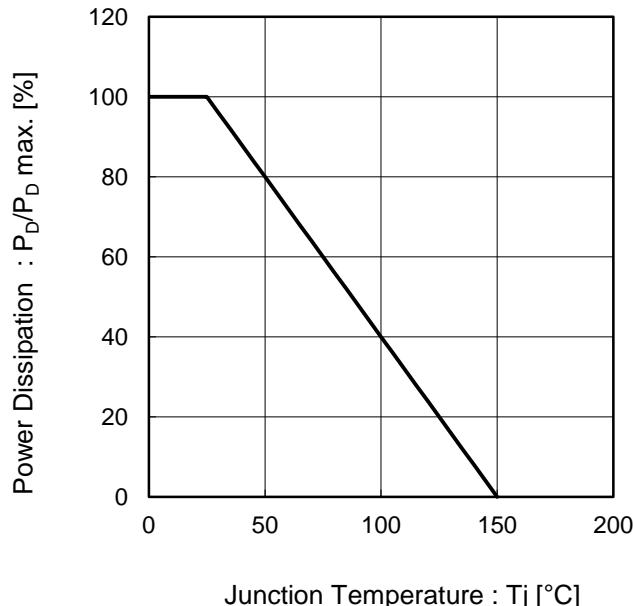


Fig.2 Maximum Safe Operating Area

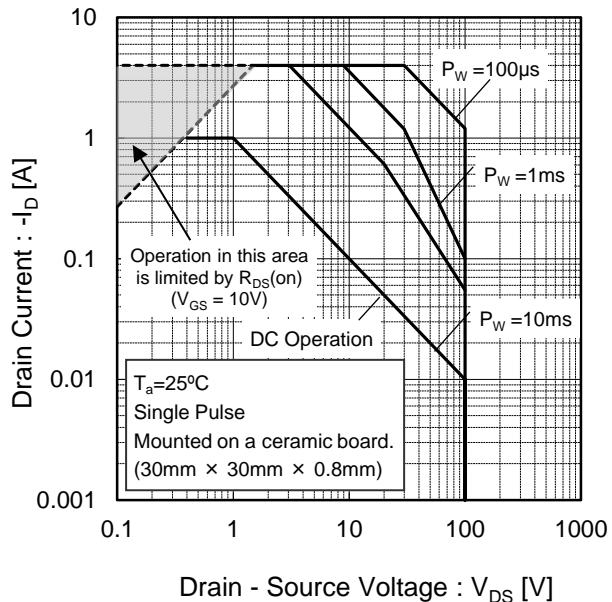


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

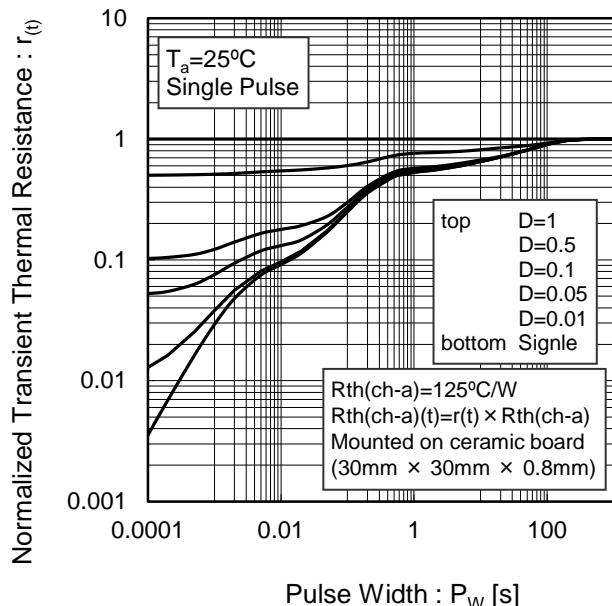
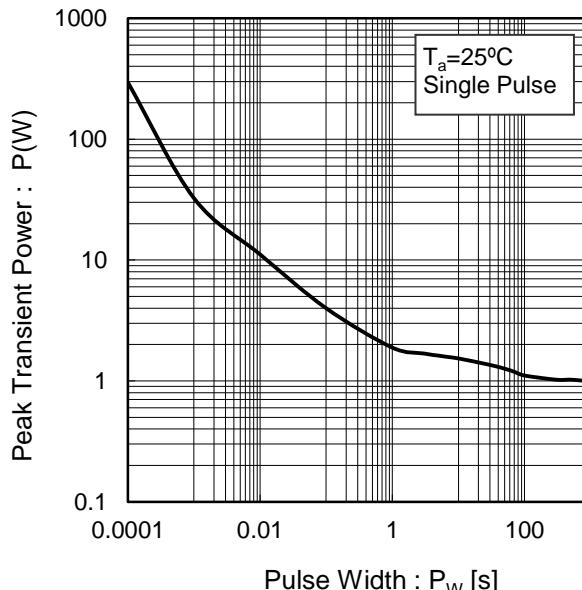


Fig.4 Single Pulse Maximum Power dissipation



●Electrical characteristic curves

Fig.5 Typical Output Characteristics(I)

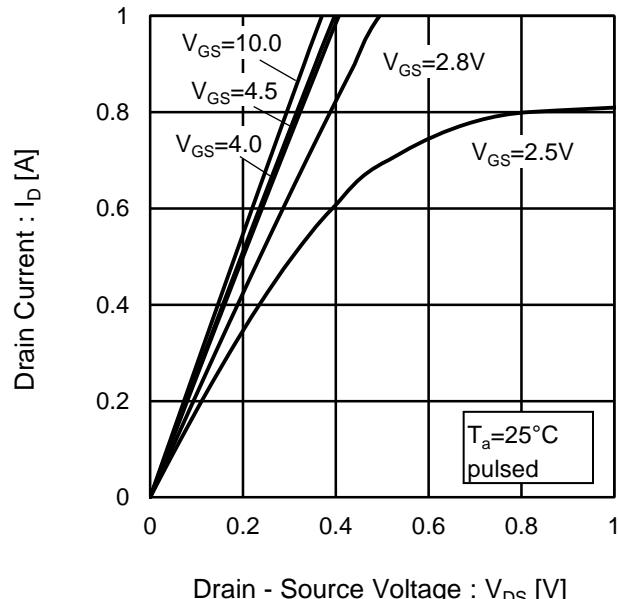
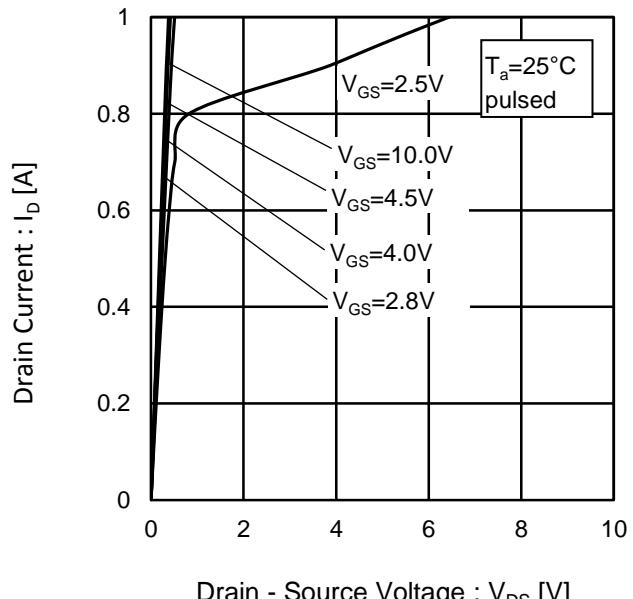


Fig.6 Typical Output Characteristics(II)



● Electrical characteristic curves

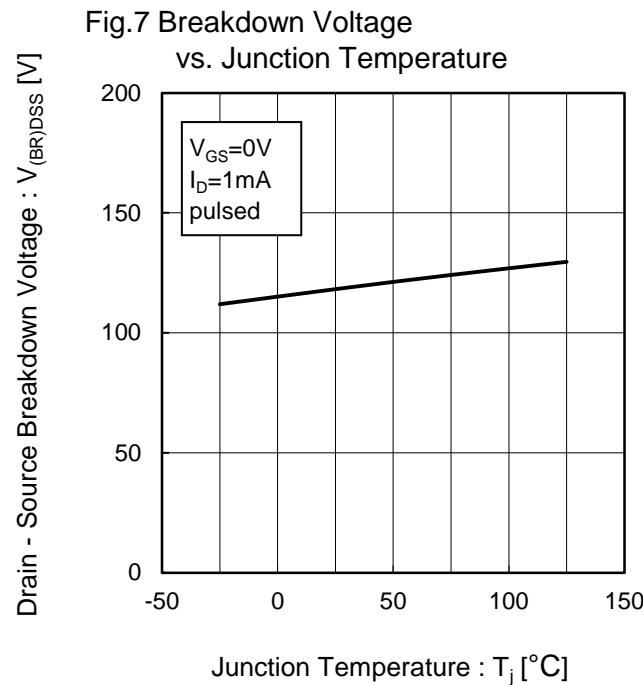


Fig.8 Typical Transfer Characteristics

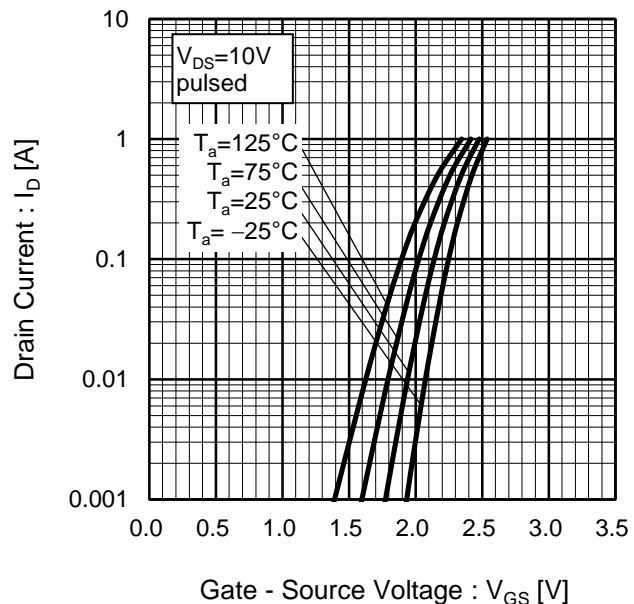


Fig.9 Gate Threshold Voltage vs. Junction Temperature

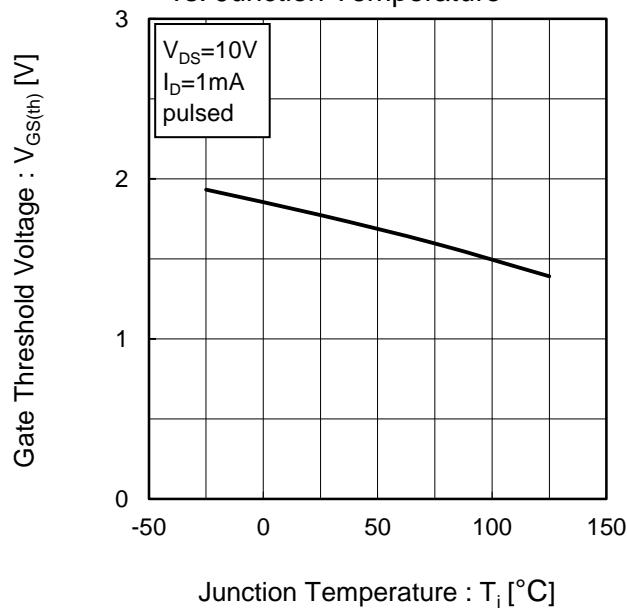
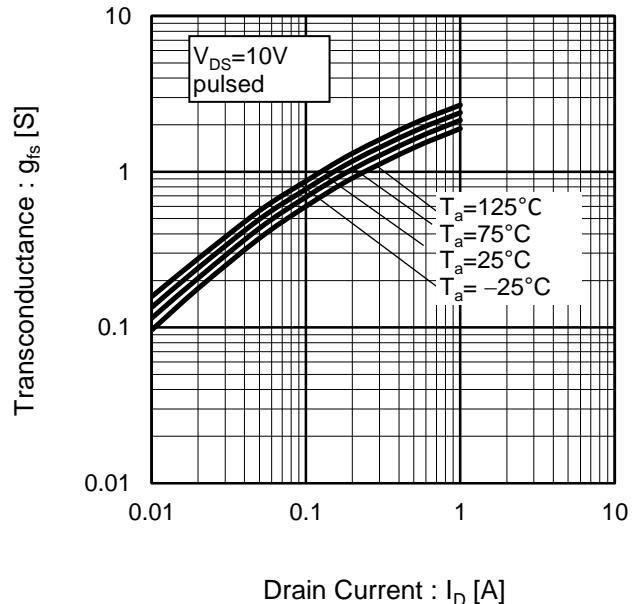


Fig.10 Transconductance vs. Drain Current



● Electrical characteristic curves

Fig.11 Drain CurrentDerating Curve

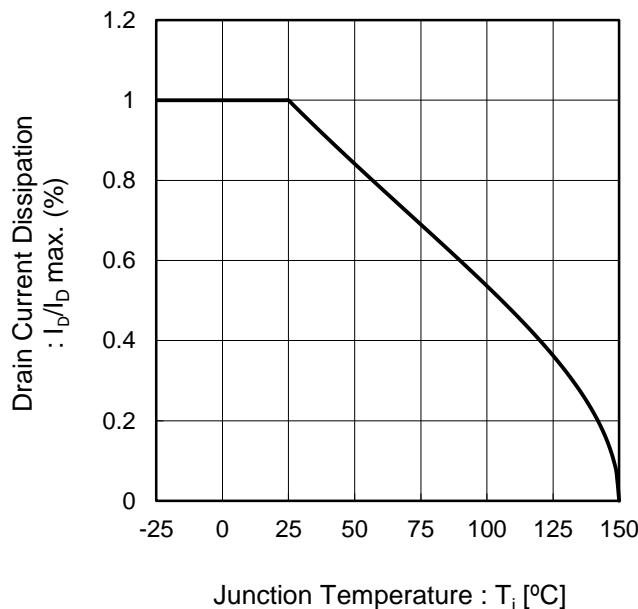


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

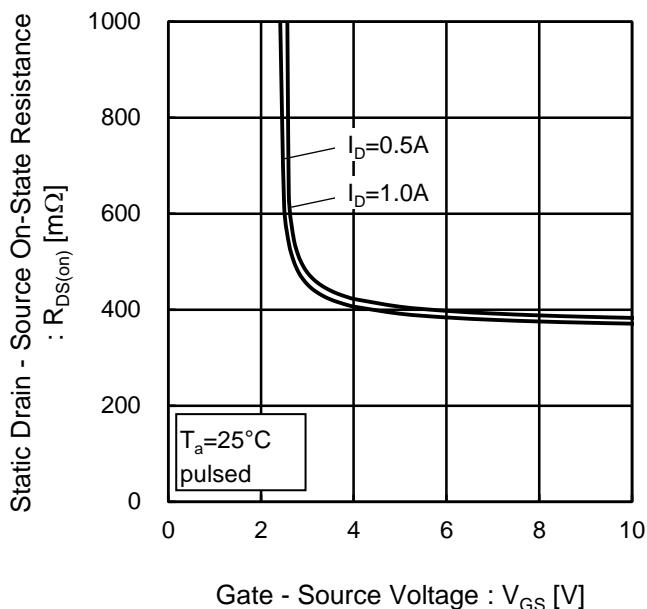


Fig.13 Static Drain - Source On - State Resistance vs. Drain Current(I)

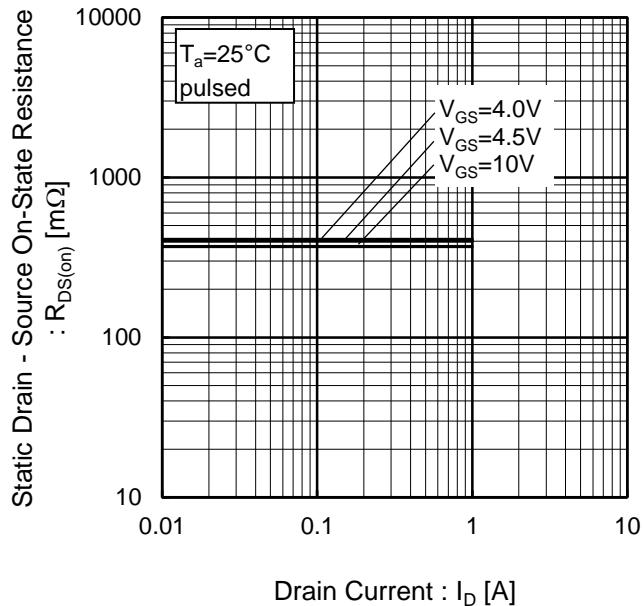
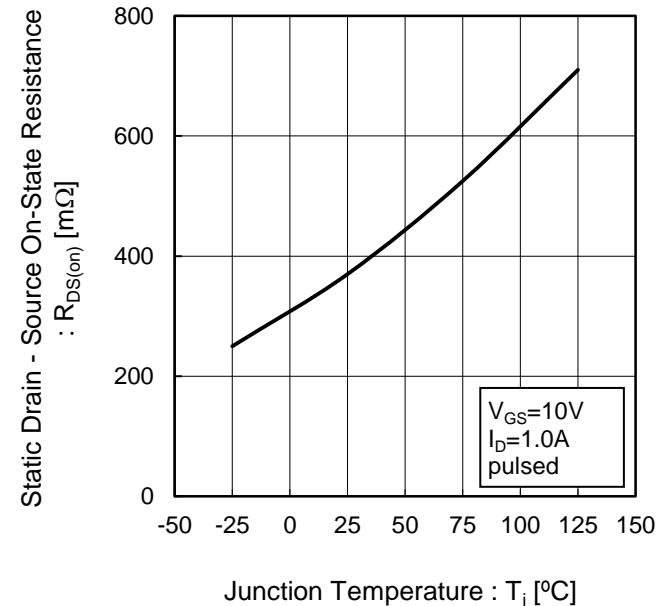


Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature



● Electrical characteristic curves

Fig.15 Static Drain-Source On-State Resistance vs. Drain Current(II)

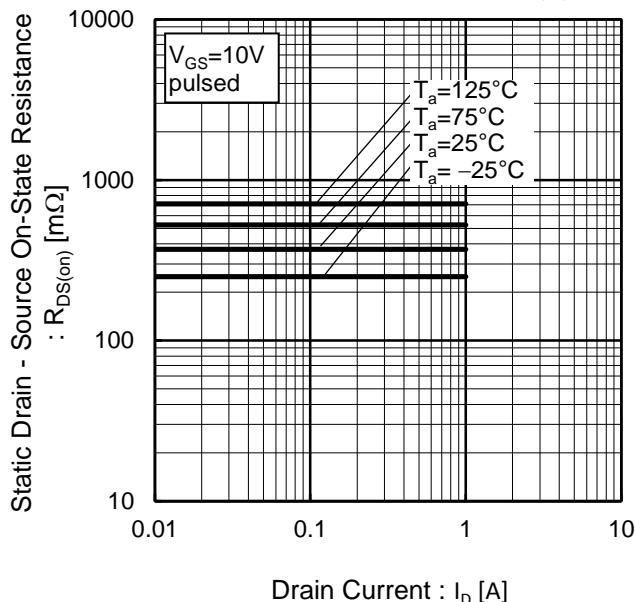


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)

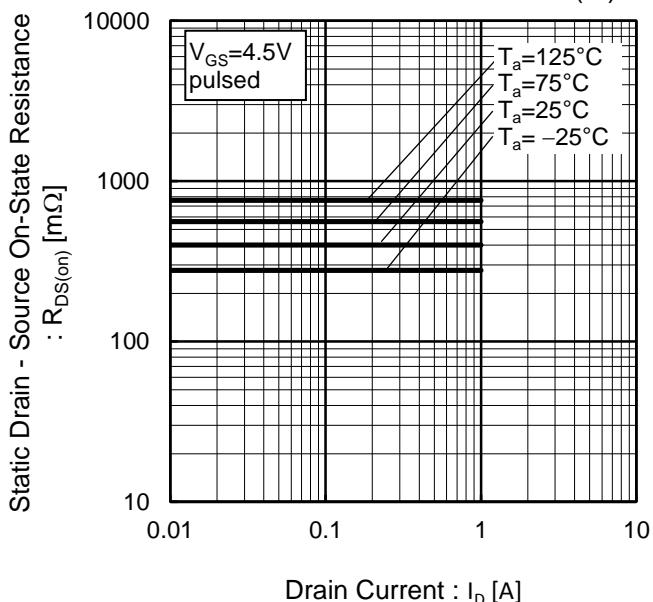
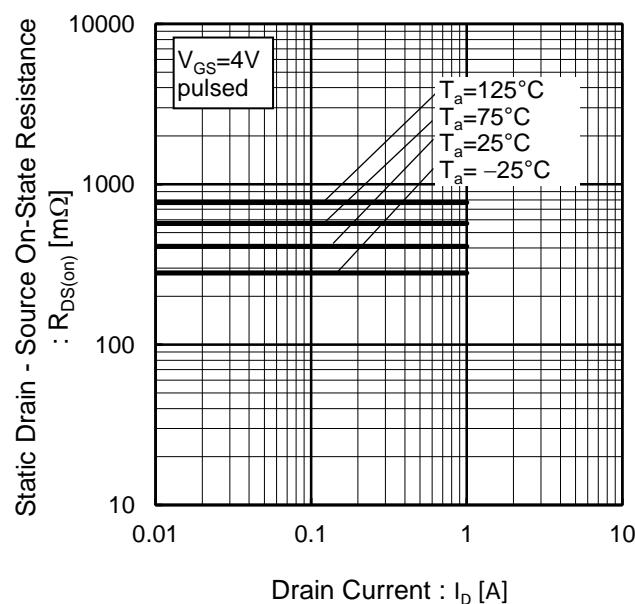


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current(IV)



●Electrical characteristic curves

Fig.18 Typical Capacitance vs. Drain - Source Voltage

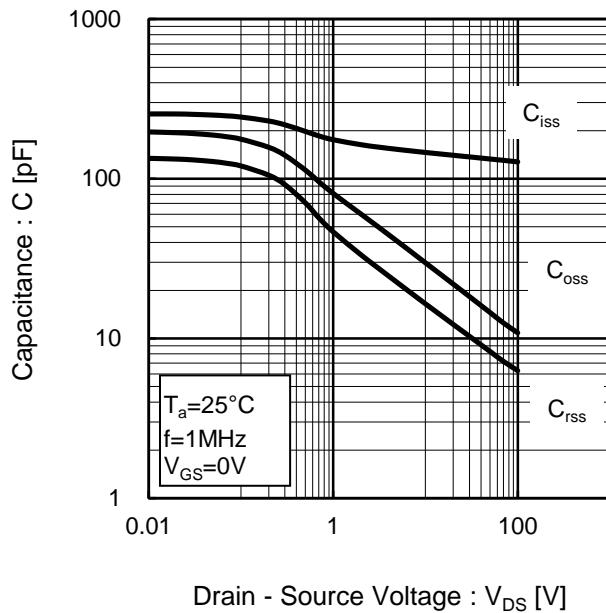


Fig.19 Switching Characteristics

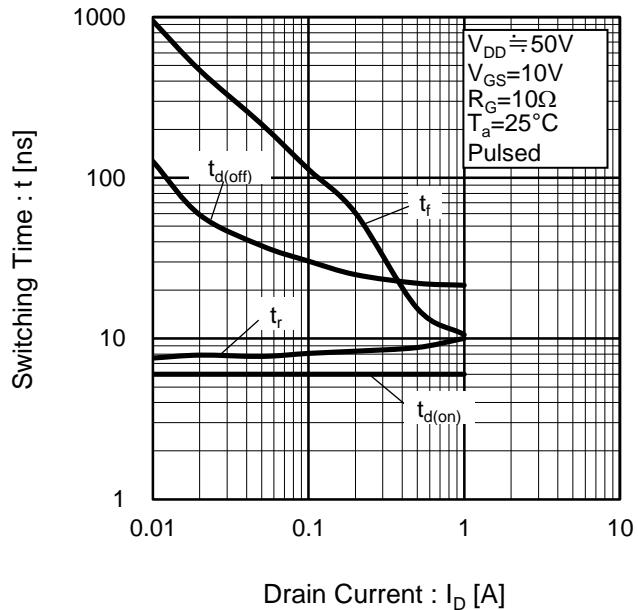


Fig.20 Dynamic Input Characteristics

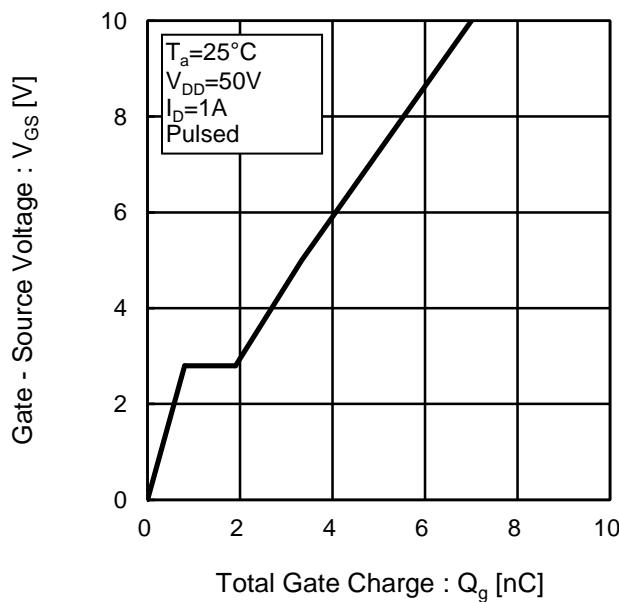
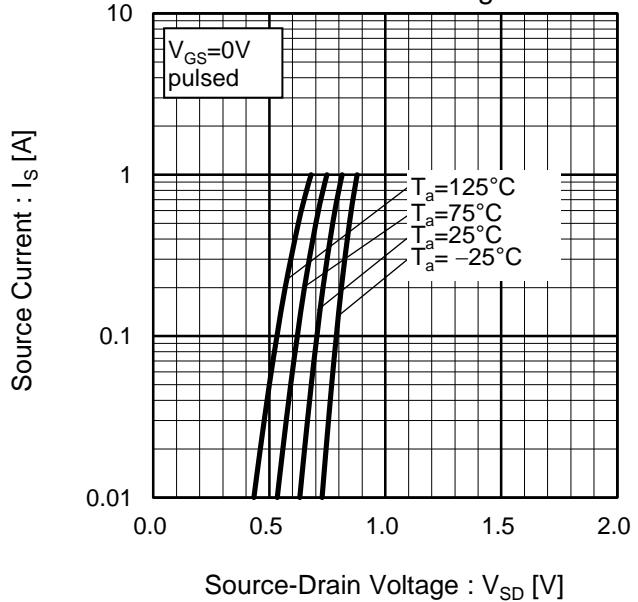


Fig.21 Source Current vs. Source Drain Voltage



●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

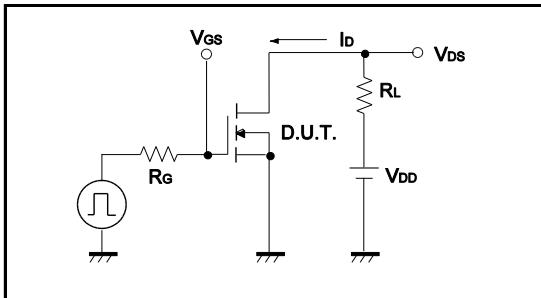


Fig.1-2 Switching Waveforms

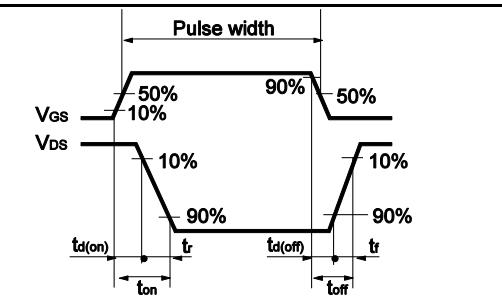


Fig.2-1 Gate Charge Measurement Circuit

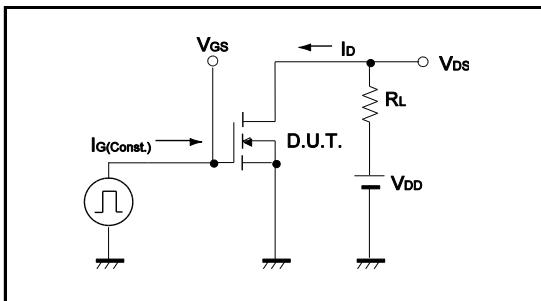
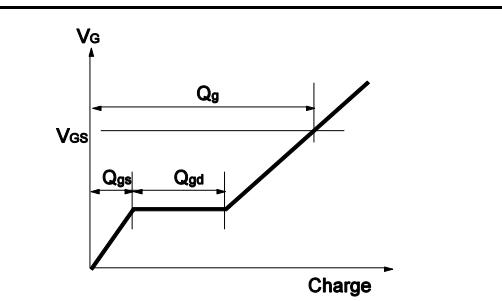
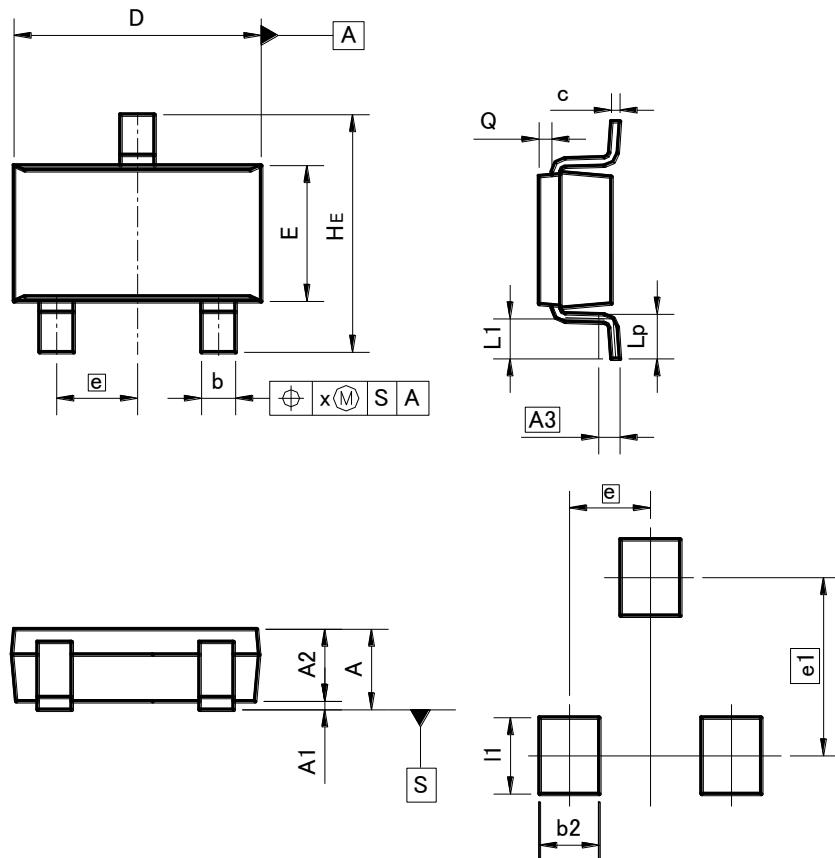


Fig.2-2 Gate Charge Waveform



●Dimensions (Unit : mm)

TSMT3



Pattern of terminal position areas

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	—	1.00	—	0.039
A1	0.00	0.10	0	0.004
A2	0.75	0.95	0.03	0.037
A3	0.25		0.01	
b	0.35	0.50	0.014	0.02
c	0.10	0.26	0.004	0.01
D	2.80	3.00	0.11	0.118
E	1.50	1.80	0.059	0.071
e	0.95		0.04	
He	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.05	0.25	0.002	0.01
x	—	0.20	—	0.008

DIM	MILIMETERS		INCHES	
	MIN	MAX	MIN	MAX
e1	2.10		0.08	
b2	—	0.70	—	0.028
I1	—	0.90	—	0.035

Dimension in mm/inches

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